



**MEGHNA BANK LTD.**  
*together we sail*

**REQUEST FOR PROPOSAL (RFP) FOR SUPPLY,  
INSTALLATION, TESTING & COMMISSIONING**

**NETWORK HSM (**Thalas Luna Network  
A700/S700**) for BACH II & NIKASH**

*Tender Ref: MGBL/PROC/RFQ/Y23/8555*

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# 1. DISCLAIMER

The information in this Request for Proposal (“RFP” or “Tender documentation”) provided to Bidders whether verbally or in documentary form by or on behalf of Meghna Bank (Bank), is provided to the Bidders on the terms and conditions set out in this RFP document and all other terms and conditions subject to which such information is provided.

This RFP is neither an agreement nor an offer and is only an invitation by Bank to the interested parties for submission of bids. The purpose of this RFP is to provide the bidders with information to assist the formulation of their proposals. This RFP does not claim to contain all the information each bidder may require. Each bidder should conduct its own investigations and analysis and check the accuracy, reliability and completeness of the information in this RFP and where necessary obtain independent advice.

Subject to any law to the contrary, and to the maximum extent permitted by Bangladesh law, Bank and its directors, officers, or employees disclaim all liability from any loss, claim, expense (including, without limitation, any legal fees, costs, charges, demands, actions, liabilities expenses or disbursements incurred therein or incidental thereto) or damage (whether foreseeable or not) (“Losses”) suffered by any person acting on or refraining from acting because of any presumptions or information (whether oral or written and whether express or implied), including forecasts, statements, estimates, or projections contained in this RFP document or conduct ancillary to it whether or not the losses arise in connection with any ignorance, negligence, inattention, casualness, disregard, omission, default, lack of care, immature information, falsification or misrepresentation on the part of Bank or any of its directors, officers, or employees.

Bank may in its absolute discretion update, amend or supplement the information in this RFP.

## 2. INTRODUCTION

Meghna Bank Limited, a prominent Private Commercial Bank in Bangladesh, is dedicated to providing wide range of services, including Retail & Corporate Banking, SME Banking, Treasury Operations, International Trade, and Scheduled Banking. To ensure required security measures during file transfer (encryption/decryption mechanism), we are in need to have Hardware Security Module.

The purpose of this Request for Proposal (RFP) document is to identify a suitable and qualified Network Hardware Security Module (HSM) provider or vendor for Meghna Bank Limited. The Network Hardware Security Module (HSM) provider or vendor should have multiple years of experience in supply & supporting Network Hardware Security Modules (HSMs) like Thales Luna Network A700 / S700. The Suppliers also must have implementation experience in any bank or non-bank financial institution (NBFi) for being eligible to participate in the bidding process. The qualified provider or vendor should have experience and capabilities to facilitate seamless integration with BACH-II and the NIKASH BEFTN project of Bangladesh Bank.

### 2.1 BID AND PROPOSAL OWNERSHIP

The proposal submitted, along with all accompanying documents and templates, exclusively belongs to Meghna Bank. No redistribution, in whole or in part, is permitted without prior written consent from the bank. Any violation of this policy constitutes a breach of trust and may lead to the Bidder's permanent disqualification. Please be informed that all proposals and accompanying documents submitted by the Bidder will become the property of Meghna Bank and shall not be returned.

### 2.2 CONFIDENTIALITY

The Bidder will be exposed by virtue of the contracted activities to internal business information of Bank, affiliates, and/or business partners. Disclosure of the aforementioned information to parties not directly involved in providing the services requested could result in the disqualification of the Bidder, pre-mature termination of the contract, or legal action against the Bidder for breach of trust.

## 3.RFP SCHEDULE

|  |                                 |
|--|---------------------------------|
| <b>RFP Reference No</b>                            | MGBL/PROC/RFQ/Y23/8555          |
| <b>Date of release of Tender</b>                   | October 18, 2023                |
| <b>Last date for submitting Queries by vendor</b>  | October 23, 2023                |
| <b>Last date for submission of response to RFP</b> | <b>October 29, 2023 4:00 PM</b> |

*\* Any bid received by the Bank after the deadline for submission of bids will be rejected and/or returned unopened to the Vendor, if so desired.*

**RFP and Inquiry Response to:** For any clarifications, please communicate with **Mr. Md Kaium Hossain**, Phone +8801787686359 & Email: Kaium.hossain@meghnabank.com.bd.

**Tender Preparation:** Tenders must be submitted in two-envelope system i.e., one Technical Proposal & one Financial Proposal mentioning Technical/Financial Proposal on the top of each envelope. These two proposals will be submitted together in a third envelope. All the envelopes should be sealed & signed.

**Submitted to:** Chairman, Procurement committee, Meghna Bank Ltd, Address: Subastu Imam Square (Level-6), 65 Gulshan Avenue, Gulshan-1, Dhaka 1212, Bangladesh.

## 4. Tender Preparation Guide

1. Tenders must be submitted in two-envelope system i.e. one Technical Proposal & one Financial Proposal mentioning Technical/Financial Proposal on the top of each envelope. These two proposals will be submitted together in a third envelope. All the envelopes should be sealed & signed.
2. The bid forms must be filled in through computer printer or in typing without overwriting and without any erasing and modifications and when completed shall contain all the required information.
3. The Offer shall be marked as “Network HSM (Thalas Luna Network A700/S700) for BACH II & NIKASH of MEGHNA BANK LIMITED”
4. Offers in the bid should be free from any condition and any conditional offer will disqualify the bidder. Unless otherwise provided herein bids shall be submitted on a firm and final price basis including all charges. Each page of the offer must be signed and sealed properly by the authorized representative of the bidder and filled in where applicable.
5. Award Finalization and subsequent actions: The Bank will award the Contract to the Bidder whose offer is found to be substantially responsive and who has offered technically suitable proposal & whose quoted price is within the acceptable limit of the Bank. After selection of the vendor, the vendor will maintain close contact with the client to sort out details of works to be undertaken.
6. Meghna Bank reserves the right to accept / Cancel / reject any or all offer without assigning any reason whatsoever.
7. In case of any error detected in the Bill of Quantities or in other documents at any time, Meghna Bank reserves the right to rectify such error.
8. Meghna Bank is not bound to accept the lowest price it will be comparison matrix goes with combined technical & financial consideration.
9. For the purpose of warranty period, work completion time will be counted from the date of installation, testing and commissioning.
10. After commencement, work may be delayed due to unforeseen reasons; in such cases, no compensation will be entertained.
11. No tender document will be issued / received by mail.
12. Tender offer may be rejected for any one of the reasons listed herein under. Decision of the Bank will be final in this regard:
  - a. Failure to submit tender before the specified closing time.
  - b. All or any pages of the tender document are not signed and sealed by the tenderer.
  - c. Failure to comply with specifications annexed herewith.
  - d. Any false statement or evidence of fraud.
  - e. Failure to comply with all the instructions of the tender.
  - f. Failure to submit any document as specified this schedule.
  - g. Any discrepancy, overwriting, erasing, ambiguity or omission in quoting rate and in furnishing the tender document.

13. Other Terms & Conditions:

- a. Bank has the right to execute full or part of the work.
- b. The Vendor should consider that the Bank can be requested to do some extra work those are not specifically mentioned in the schedule, but might be necessary for the completion of the work.
- c. No tender will be accepted for partial quantity.
- d. The bid owner must maintain "Business Account" with Meghna Bank Limited. All Payment will be disbursed through the Business Account.

14. Delivery:

- a. Delivery period: To be mentioned by the bidder.
- b. Delivery of the items to be made at IT Division/Head Office or designated place as desired by the Bank.
- c. Penalty for Delay in delivery: For any delay in delivery and implementation of the system solely due to failure on the part of the BIDDER, the BIDDER will be subject to penalty charges of 0.5% per week of total price.

## 5. BIDDER RESPONSES GUIDE

1. The Bank will only consider the Bids that are prepared as per the formats mentioned in this RFP Annexure 6.
2. Bidder must supply all the requirement items mentioned in Annexure 1. Whether it is a built-in feature or requires customization by the bidder is not relevant to the bank. Those items should be covered in the commercial proposal.
3. "TECHNICAL PROPOSAL BID" will not contain any pricing or commercial information at all.
4. The Vendor should quote the price as per "Financial Template" (Annexure 3).
5. Any additional information (e.g.: brochures, client testimonials etc.) should be not be included in the Request for Proposal. Bank will have asked later if required.

## 6. BID OPENING AND EVALUATION

1. In the first stage, only Technical proposal will be opened and evaluated.
2. All received RFP responses will be evaluated as per the eligibility criteria.
3. In the second stage, the Financial proposal of only those Vendors, whose technical proposal are short-listed, will be opened.
4. Bank will examine the financial bids to determine whether they are complete; whether any computational errors have been made; whether required information has been provided as underlined in the bid document; whether the documents have been properly signed, and whether bids are generally in order. Bids from agents without proper authorization from the manufacturer as per the authorization form, shall be treated as non-responsive and will be out rightly rejected.
5. To assist in the examination, evaluation and comparison of bids the Bank may, at its discretion, ask the Vendor for clarification.
6. The Bank will follow staged evaluation and selection process comprising of Technical and Commercial evaluation. The Bank's Board will have the ultimate right to make the final decision. The decision of the Bank would be final and the Bank may accept or reject an offer without assigning any reason what so ever.



# ANNEXURE 1 - SCOPE OF WORK

*Note: The bidder must supply all items mentioned in this section. Whether it is a built-in feature or requires customization by the bidder is not relevant to the bank*

## HSM TECHNICAL SPECIFICATION:

| SL.No | Technical Specification     |  |
|-------|-----------------------------|--|
|       | Name of Item                | Description  |
| 1     | Brand                       | Thalas Network HSM   |
| 2     | Model                       | Luna A700 / S700   |
| 3     | No of HSM                   | 03 HSM (From Day one 5 partition for each HSM will be activated)   |
| 4     | Driver Version              | Firmware 7.0.3 and Luna Client drivers 7.2.0   |
| 5     | TPS                         | 1000/s   |
| 6     | Cryptographic interfaces    | Full Suite B support • Asymmetric: RSA, DSA, Diffie-Hellman, Elliptic Curve Cryptography (ECDSA, ECDH, Ed25519, ECIES) with named, user-defined and Brainpool curves, KCDSA, and more • Symmetric: AES, AES-GCM, Triple DES, DES, ARIA, SEED, RC2, RC4, RC5, CAST, and more • Hash/Message Digest/HMAC: SHA-1, SHA-2, SHA-3, SM2, SM3, SM4 and more • Key Derivation: SP800-108 Counter Mode • Key Wrapping: SP800-38F • Random Number Generation: designed to comply with AIS 20/31 to DRG.4 using HW based true noise source alongside NIST 800-90A compliant CTR-DRBG • Digital Wallet Encryption: BIP32 • 5G Cryptographic Mechanisms for Subscriber Authentication: Milenage, Tuak, and COMP128 |
| 7     | Supported Operating Systems | <ul style="list-style-type: none"> <li>Windows, Linux, Solaris, AIX</li> <li>Virtual: VMware, Hyper-V, Xen, KVM.</li> </ul>  |
| 8     | API Support                 | PKCS#11, Java (JCA/JCE), Bouncy Castle APIs should be supported REST API for administration. Should support Customized and Validated Firmware and API for BACH II  |
| 9     | Partitions                  | Should support partitioning of FIPS 140-2 certified HSM memory into completely isolated divisions and not just logical partitioning in associated software with each partition managed by their own Security Officer and Crypto Officer Roels and having independent security policies that can be managed. From Day one 5 partition for each HSM will be activate.  |
| 10    | Security Certifications     | <ul style="list-style-type: none"> <li>FIPS 140-2 Level 3 – Password or Multifactor PED</li> <li>Common Criteria EAL4+ (AVA_VAN.5 and ALC_FLR.2) against the Protection Profile EN 419 221-5</li> <li>Qualified Signature or Seal Creation Device (QSCD) listing for eIDAS compliance</li> <li>Singapore NITES Common Criteria Scheme</li> </ul>   |

|    |                                   |  |
|----|-----------------------------------|--|
| 11 | Host Interface                    | <ul style="list-style-type: none"> <li>• 4 x 1G with Port Bonding</li> <li>• IPv4 and IPv6</li> </ul>  |
| 12 | Physical Characteristics          | Standard 1U 19in. rack mount appliance • Dimensions: 19" x 21" x 1.725" (482.6mm x 533.4mm x 43.815mm) • Weight: 28lb (12.7kg) • Input Voltage: 100-240V, 50-60Hz • Power Consumption: 100W maximum, 84W typical • Heat Dissipation: 376BTU/hr maximum, 287BTU/hr typical • Temperature: operating 0°C – 35°C, storage -20°C – 60°C • Relative Humidity: 5% to 95% (38°C) non-condensing |
| 13 | Safety & Environmental Compliance | • UL, CSA, CE • FCC, CE, VCCI, C-TICK, KC Mark • RoHS2, WEEE • TAA • India BIS [IS 13252 (Part 1)/IEC 60950-1]   |
| 14 | Reliability                       | Dual hot-swap power supplies • Field-serviceable components • Mean Time Between Failure (MTBF) 171,308 hrs   |
| 15 | Management & Monitoring           | • HA disaster recovery • Backup and restore hardware to hardware on-premises or in the cloud • SNMP, Syslog  |
| 16 | Backup                            | HSM should be compatible with existing Backup HSM Devices available with the bank and should be usable with the provided HSM for backup and recovery.  |
| 17 | Key Migration                     | Provided HSM should support Key Migration from existing HSM model in BACH.   |
| 18 | Warranty                          | 3 years warranty 24x7 Telephonic and Email provided directly from OEM  |
| 19 | Training                          | 5-person training in OEM certified training Lab with certified trainer free of cost.   |
| 20 | BB Confirmation                   | Awardee vendor will have to submit confirmation or certification from Bangladesh bank on the network HSM for BACH-II, Nikash & IDTP project.   |

**WORK COMPLETION TIME:**

1. The client will issue a work-order to the successful bidder upon acceptance of the offer.
2. Work must be completed within the time specified in the work order/Notification of Award.

**QUALITY ASSURANCE:**

1. The Vendor shall comply with the technical specification as mentioned in the Tender Schedule.

**TRAINING FOR OPERATION & TROUBLESHOOTING:**

1. Product related full system administration/certification training from OEM or certified solution center for 5 people.

# ANNEXURE 2 - WARRANTY, AMC & AFTER SALES SERVICE

High level Service Level Agreement (SLA):

Support Type:

| Severity Level | General Evaluation Criteria  | Response Time (24/7/365)                      | Resolution Time (24/7/365) |
|----------------|--|---|----------------------------|
| High           | A problem that critically effects on ability of doing regular business. System functionality is unavailable or down due to hardware or software failure. | By Email/Phone: 15 Minutes<br>Onsite: 01 Hour | 02 hours                   |
| Medium         | Any Hardware or software component failure that leads to degradation of system performance.  |   | 04 Hours                   |
| Low            | System is having minor issue. Insignificant error without impacting usual business or system performance.  |   | 08 Hours                   |

## Penalty Clause on Service Failure

1. 1% of the work order value will be penalized on each failure to meet service level.
2. If resolution time is greater than agreed service level, then 0.5% will be penalized for each hour delay for severity level 'High' and 0.25% will be penalized for each hour delay for severity level 'Medium' and 'Low'.

## Scope of Warranty Service:

The scope of service is as below but not limited to:

1. Complete diagnosis and replacement (if needed) will be carried out by bidder local partner
2. Install, configure and commission of the HSM as per requirement of the Bank.
3. Maintain all the hardware and software of the Server systems by 24/7/365 days without any interruption.
4. Ensure resource or emergency product support If required any application/server related maintenance from Meghna Bank Limited.
5. OEM & Local vendor provide till date patch, firmware, software up-gradation, Security Enhancement, vulnerability mitigation as required to maintain compliance and standard practice preferably without any service interruption within the Warranty/AMC period, with shortest time of the component release.
6. Bridge between OEM, Local partner and Meghna Bank for knowledge transfer, problem troubleshoot and best use of the product.
7. Ensure that Meghna Bank can use all the product facilities as and when required
8. To ensure single point of contact, backup contact and support contact escalation matrix
9. To provide a quarterly report of the health status of the Server system along with performance forecast and performance improvement plan.
10. All services and supplied parts, labour, transport and logistic cost is inclusive in the Warranty/AMC amount.
  - a. OEM & vendor will ensure the Warranty, AMC & Support service
  - b. Vendor to quote AMC & Support for 3 years.
  - c. Vendor to quote 4th & 5th year AMC separately for the offered solution for each type of product.
  - d. Meghna Bank should have direct access to OEM portal to log a case and communicate with OEM global support on any issue.

11. Ensure the new integration hosts/servers/backup system/storage/software/security items as per requirement of the Bank
12. Vendor must repair any defect/replace any parts of the solution and render services in connection there to at its own cost.



# ANNEXURE 4 - OFFER COVERING LETTER

**The Chairman,**

Procurement Committee,

Meghna Bank Ltd,

Subastu Imam Square,

65 Gulshan Avenue, Gulshan-1,

Dhaka 1212, Bangladesh.

Dear Sir,

Re: Response to RFP No. MGBL/PROC/RFQ/Y23/8555

We have reviewed and understood the contents, instructions, and terms and conditions outlined in your Request for Proposal (RFP) referenced as above. With this letter, we submit our proposal to provide the specified Network HSM (Thalas Luna Network A700/S700) as detailed in the aforementioned RFP.

We affirm that our proposal is compliant with the terms and conditions laid out in the RFP and any subsequent amendments, if applicable. We fully acknowledge and accept all the terms and conditions stipulated in the RFP.

Enclosed with this submission are the requisite documents that constitute our complete bid package.

It is duly noted that Meghna Bank reserves the right to accept or reject the bid, either in its entirety or in part. The bank also retains the authority to annul the entire tendering process without being obligated to furnish any grounds for such actions.

Yours sincerely,

Signature:

Name:

Designation:

Date:

Seal:

## ANNEXURE 5 - SELF DECLARATION BLACKLISTING

The Chairman,  
Procurement Committee,  
Meghna Bank Ltd,  
Subastu Imam Square,  
65 Gulshan Avenue, Gulshan-1,  
Dhaka 1212, Bangladesh.

Dear Sir,

Re: Response to RFP No. MGBL/PROC/RFQ/Y23/8555

We hereby certify that we have not been blacklisted in any Central Government / Regulatory / Banking / Insurance company in Bangladesh as on date of the RFP.

Yours sincerely,

Signature:

Name:

Designation:

Date:

Seal:

## ANNEXURE 6 – CHECK LIST

Bidders have to ensure the submission of the bids enclosing the below mentioned documents with details filled in completely, wherever required. All these documents should be duly signed by the bidder or the person authorized to sign on behalf of the bidder. The bids received without any of these documents or with incomplete details will summarily may be rejected.

| SL No. | Document   | Part of    | Send via |
|--------|--|------------|----------|
| 1      | Complete RFP document duly signed by Authorized signatory on every page, for having read and understood all the terms and conditions of the RFP. | Functional | Physical |
| 2      | Annexure – 4 : Offer Covering Letter   | Functional | Physical |
| 3      | Letter of Authorization / Undertaking  | Functional | Physical |
| 4      | Undertaking for being the OEM of the offered product / Manufacturer Authorization letter   | Functional | Physical |
| 5      | Annexure – 5 : Self Declaration – Black Listing  | Functional | Physical |
| 6      | Annexure – 1 : SCOPE OF WORK - Network HSM : Technical Specification   | Functional | Physical |
| 7      | Annexure – 2 : WARRANTY, AMC & AFTER SALES SERVICE   | Technical  | Physical |
| 8      | Sealed Commercial Bid (Annexure 3) as per financial template   | Commercial | Physical |